

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Yen-Yi Wu	07/17/2007
Wei-Yueh Sung	07/19/2007
Pao-Huei Chang Chien	07/23/2007
Chi-Chih Chu	07/17/2007
Cheng-Yin Lee	07/18/2007
Gwo-Liang Weng	07/17/2007
RECEIVING PARTY DATA	
Name:	Advanced Semiconductor Engineering, Inc.
Street Address:	26 Chin 3rd Rd., Nantze Export Processing Zone
City:	Kao-Hsiung City
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11828352
CORRESPONDENCE DATA	
Fax Number:	(703)997-4517
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	3027291562
Email:	Patent.admin.uspto.cr@naipo.com
Correspondent Name:	WINSTON HSU
Address Line 1:	P.O.BOX 506
Address Line 4:	Merrifield, VIRGINIA 22116
ATTORNEY DOCKET NUMBER:	ASEP0084USA
NAME OF SUBMITTER:	WINSTON HSU

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Total Attachments: 3

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ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNOR(S) (Inventors):

Name: Yen-Yi Wu Nationality: R.O.C.

Name: Wei-Yueh Sung Nationality: R.O.C.

Name: Pao-Huei Chang Chien Nationality: R.O.C.

Name: Chi-Chih Chu Nationality: R.O.C.

Name: Cheng-Yin Lee Nationality: R.O.C.

Name: Gwo-Liang Weng Nationality: R.O.C.

Hereby sells, assigns and transfers to

ASSIGNEE(S):

Name: Advanced Semiconductor Engineering, Inc.

Address: 26 Chin 3rd Rd., Nantze Export Processing Zone, Kao-Hsiung City, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"Method of making a semiconductor package and method of making a semiconductor device"

Which is found in :

(a) + U.S. patent application executed on even date

PATENT

- (b) _____ U.S. patent application executed on _____
(c) _____ U.S. application serial no. _____
(d) _____ patent no. _____ issued _____

NPO#ASE-P0084-USA:0
CUST#ASE1808-1

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and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this _____ (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Signature of INVENTOR

Yen-Yi Wu

Yen-Yi Wu 2007/07/17

Wei-Yueh Sung

Wei-Yueh Sung JUL 19 2007

Pao-Huei Chang Chien

Pao-Huei Chang Chien JUL 23 2007

Chi-Chih Chu

Chi-Chih Chu 2007/07/17

Cheng-Yin Lee

Cheng-Yin Lee 2007/07/18

Gwo-Liang Weng

Gwo-Liang Weng 2007/07/17